

## C0603C103F3GECTU

Aliases (C0603C103F3GEC7867)

ESD SMD Comm COG, Ceramic, 0.01 uF, 1%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0603



Click [here](#) for the 3D model.

### Dimensions

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.07mm
S	0.7mm MIN
B	0.35mm +/-0.15mm

### Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

### General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.